

# HD74SSTV16842

# 11-bit to 22-bit Buffer with SSTL\_2 Inputs and Outputs

REJ03D0829-0200 (Previous: ADE-205-602A) Rev.2.00 Apr 07, 2006

## Description

The HD74SSTV16842 is a 11-bit to 22-bit buffer designed for 2.3 V to 2.7 V Vcc operation and SSTL\_2 data (A) inputs.

## Features

- Supports SSTL\_2 data inputs
- Flow through architecture optimizes PCB layout
- Ordering Information

Part Name	Package Type	Package Code (Previous code)	Package Abbreviation	Taping Abbreviation (Quantity)	
HD74SSTV16842TEL	TSSOP-64 pin	PTSP0064KA-A		EL (1,000 pcs / Reel)	
		(TTP-64DV)			

# **Function Table**

		Input A				
		L		20	L	
		Н			Н	
Η:	High level					
L :	Low level					

Not no



# **Pin Arrangement**

Y11A	1 6	4 V <sub>DDQ</sub>
		3 GND
	3 6	2 A11
Y9A	4 6	1 A10
Y8A	5 6	0 V <sub>CC</sub>
V <sub>DDQ</sub>		9 V <sub>DDQ</sub>
GND	7 5	8 GND
Y7A	8 5	7 A9
Y6A	9 5	6 A8
Y5A 1	0 5	5 V <sub>DDQ</sub>
GND 1	1 5	4 GND
Y4A 1		3 A7
Y3A 1		2 A6
Y2A 1		
GND 1		0 GND
Y1A 1		
Y11B 1		8 NC
V <sub>DDQ</sub> 1		7 VDDQ
Y10B 1		6 Vcc
Y9B 2		5 V <sub>REF</sub>
Y8B 2		4 A5
GND 2		3 GND
Y7B 2		2 V <sub>DDQ</sub>
Y6B 2		1 A4
Y5B 2		
GND 2		9 GND
VDDQ 2	3	8 V <sub>DDQ</sub>
Y4B		
Y3B 2 GND 3		6 A2 5 A1
Y2B		a A1 4 GND
Y1B		3 V <sub>DDQ</sub>
	(Top view)	



### **Absolute Maximum Ratings**

ltem	Symbol	Ratings	Unit	Conditions
Supply voltage	$V_{CC} \text{ or } V_{DDQ}$	-0.5 to 3.6	V	
Input voltage <sup>*1</sup>	VI	-0.5 to V <sub>DDQ</sub> +0.5	V	
Output voltage *1, 2	Vo	-0.5 to V <sub>DDQ</sub> +0.5	V	
Input clamp current	I <sub>IK</sub>	±50	mA	$V_I < 0 \text{ or } V_I > V_{CC}$
Output clamp current	Ι <sub>οκ</sub>	±50	mA	$V_{\rm O}$ < 0 or $V_{\rm O}$ > $V_{\rm DDQ}$
Continuous output current	lo	±50	mA	$V_0 = 0$ to $V_{DDQ}$
$V_{CC}$ , $V_{DDQ}$ or GND current / pin	I <sub>CC</sub> , I <sub>DDQ</sub> or I <sub>GND</sub>	±100	mA	
Maximum power dissipation at Ta = 55°C (in still air)	P <sub>T</sub>	1	W	TSSOP
Storage temperature	Tstg	-65 to +150	°C	

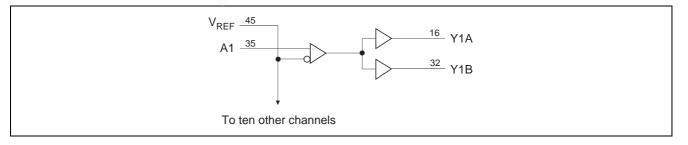
Notes: Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute maximum rated conditions for extended periods may affect device reliability.

- 1. The input and output negative voltage ratings may be exceeded if the input and output clamp current ratings are observed.
- 2. This current will flow only when the output is in the high state and  $V_0 > V_{DDQ}$ .

## **Recommended Operating Conditions**

Item	Symbol	Min	Тур	Max	Unit	Conditions
Supply voltage	Vcc	V <sub>DDQ</sub>	2.5	2.7	V	
Output supply voltage	V <sub>DDQ</sub>	2.3	2.5	2.7	V	
Reference voltage	V <sub>REF</sub>	1.15	1.25	1.35	V	$V_{\text{REF}} = 0.5 \times V_{\text{DDQ}}$
Termination voltage	V <sub>TT</sub>	V <sub>REF</sub> -40 mV	V <sub>REF</sub>	V <sub>REF</sub> +40 mV	V	
Input voltage	VI	0		Vcc	V	
AC high level input voltage	VIH	V <sub>REF</sub> +310 mV		_	V	A
AC low level input voltage	VIL			V <sub>REF</sub> -310 mV	V	A
DC high level input voltage	VIH	V <sub>REF</sub> +150 mV	× -	—	V	A
DC low level input voltage	VIL	-43	—	V <sub>REF</sub> -150 mV	V	A
High level output current	Іон		_	-20	mA	
Low level output current	OL		—	20	mA	
Input transition rise or fall time	$\Delta t / \Delta v$	_	—	10	ns/V	
Operating temperature	Та	0	—	70	°C	

# Logic Diagram





### **Electrical Characteristics**

Item		Symbol	V <sub>cc</sub> (V)	Min	Тур	Max	Unit	Test Conditions
Input diode voltage		VIK	2.3	—	_	-1.2	V	I <sub>IN</sub> = -18 mA
Output voltage		V <sub>OH</sub>	2.3 to 2.7	V <sub>CC</sub> -0.2	_	—	V	I <sub>OH</sub> = −100 μA
			2.3	1.95	_	V <sub>DDQ</sub>		I <sub>OH</sub> = -16 mA
		V <sub>OL</sub>	2.3 to 2.7	—	_	0.2		I <sub>OL</sub> = 100 μA
			2.3	0	_	0.35		I <sub>OL</sub> = 16 mA
Input current	(All inputs)	I <sub>IN</sub>	2.7	—	_	±5	μA	V <sub>IN</sub> = 2.7 V or 0
Quiescent supply	Quiescent supply current		2.7	—	_	45	mA	$V_{IN} = V_{IH(AC)}$ or $V_{IL(AC)}$ , $I_O = 0$
Dynamic operatii	ng per each	I <sub>CCD</sub> <sup>*2</sup>	2.7	—	_	20	μA/	$V_{I} = V_{IH(AC)} \text{ or } V_{IL(AC)},$
data input							data	One data input switching at
							input	50% duty cycle.
Output high *3		r <sub>он</sub>	2.3 to 2.7	7	—	20	Ω	I <sub>OH</sub> = -20 mA
Output low <sup>*3</sup>		r <sub>oL</sub>	2.3 to 2.7	7	_	20	Ω	I <sub>OL</sub> = 20 mA
$ \mathbf{r}_{OH} - \mathbf{r}_{OL} $ each separate bit <sup>*3</sup>		r <sub>O(Δ)</sub>	2.5	—	_	4	Ω	I <sub>0</sub> = 20 mA, Ta = 25°C
	Data inputs	C <sub>IN</sub>	2.5 <sup>*1</sup>	2.5	_	3.5	pF	$V_{I} = V_{REF} \pm 310 \text{ mV}$
capacitance								

Notes: 1. All typical values are at V<sub>CC</sub> = 2.5 V, Ta = 25°C.

- 2. Total I<sub>CC</sub> (max) = I<sub>CC</sub> + {I<sub>CCD</sub> (Data)  $\times$  11}
- 3. This is effective in the case that it did terminate by resistance.

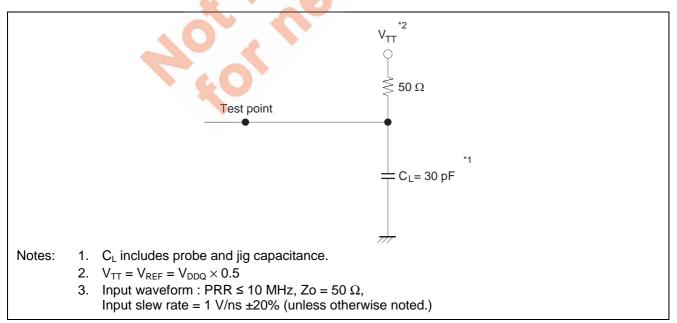
## Switching Characteristics

 $V_{CC} = 1.8 \pm 0.15 \text{ V}$ 

						cc	
Item	Symbol	$V_{\rm CC} = 2.5 \pm 0.2  \rm V$		V 🥑	Unit	FROM	то
nem	Symbol	Min	Тур	Max	Onit	(Input)	(Output)
Propagation delay time <sup>*1</sup>	t <sub>PLH</sub>	1.6	$\sim$ $-$	2.8	ns	А	Y
	t <sub>PHL</sub>						

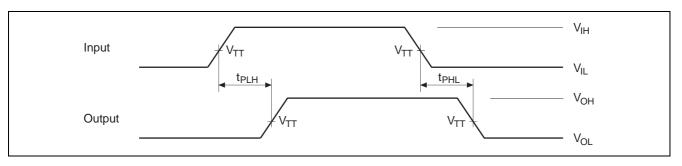
Note: 1. This timing relationship is specified into test load (see waveforms – 1) with all of the outputs switching.

# **Test Circuit**



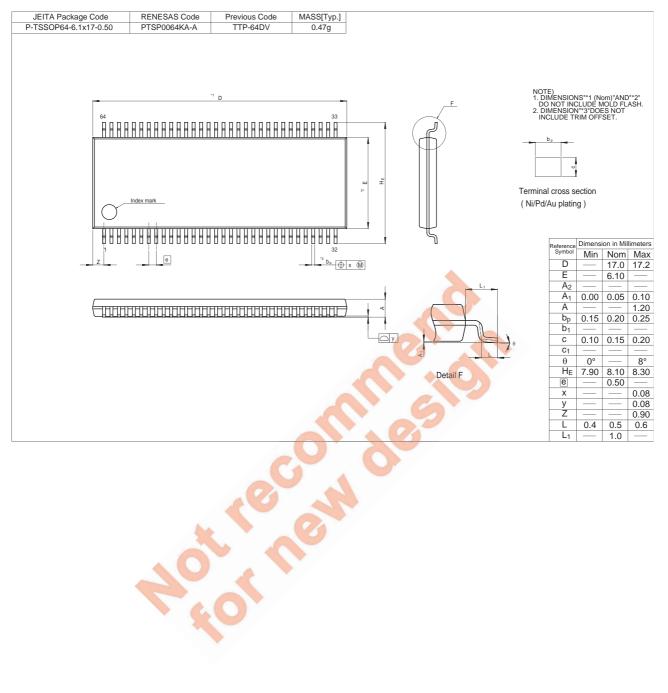


### Waveforms





# **Package Dimensions**





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